

PCN Number:	20240808002.0.A	PCN Date:	November 22, 2024
Title:	Datasheets for SNx4AHC00, SNx4AHCT04, SNx4AHCT08, SNx4AHC02, SNx4AHC74, SNx4AHC125, SNx4AHC126, SNx4AHCT02, SNx4AHCT74, SNx4AHCT125, SNx4AHCT126, SN74AHC132, SN74AHCT126-Q1, SN74AHCT125-Q1, SN74AHCT32-Q1, SN74AHCT00Q-Q1, SN74AHC14Q-Q1, SN74AHC32Q-Q1, SN74AHC74Q-Q1, SN74AHCT08Q-Q1, SN74AHCT14Q-Q1, SNx4AHC14, and SNx4AHC08		
Customer Contact:	Change Management team	Dept:	Quality Services
Change Type:	Electrical Specification		

PCN Details

Description of Change:

Texas Instruments Incorporated is announcing an information only notification. The product datasheet(s) is being updated as summarized below. The following change history provides further details.



SN54AHC00, SN74AHC00
SCLS227M – OCTOBER 1995 – REVISED MAY 2024

Changes from Revision L (February 2024) to Revision M (May 2024)	Page
• Added package size to <i>Device Information</i> table.....	1
• Updated images and table in <i>Pin Configuration and Functions</i> section.....	3
• Updated image in <i>Layout Example</i>	10

Changes from Revision K (June 2023) to Revision L (February 2024)	Page
• Updated R θ JA value: RGY = 47 to 87.1, all values in °C/W	6



SN54AHCT04, SN74AHCT04
SCLS232R – OCTOBER 1995 – REVISED FEBRUARY 2024

Changes from Revision Q (October 2023) to Revision R (February 2024)	Page
• Updated thermal values for NS package from R θ JA = 98.6 to 120.9, R θ JC(top) = 54.1 to 78.2, R θ JB = 57.4 to 81.6, Ψ JT = 19.6 to 42.8, Ψ JB = 57.0 to 81.1, R θ JC(bot) = N/A, all values in °C/W	5



SN54AHCT08, SN74AHCT08
SCLS237P – OCTOBER 1995 – REVISED OCTOBER 2023

Changes from Revision O (May 2023) to Revision P (October 2023)	Page
• Updated R θ JA values: D = 97.5 to 124.5; Updated D package for R θ JC(top), R θ JB, Ψ JT, Ψ JB, and R θ JC(bot), all values in °C/W	6



SN74AHC32, SN54AHC32
SCLS247L – OCTOBER 1995 – REVISED FEBRUARY 2024

Changes from Revision K (October 2023) to Revision L (February 2024)	Page
• Updated R θ JA value: D = 86 to 124.6, all values in °C/W	6

Changes from Revision J (May 2023) to Revision K (October 2023)	Page
• Updated R θ JA values: PW = 113 to 147.7, all values in °C/W	6

Changes from Revision M (June 2023) to Revision N (February 2024) Page

- Added package size to *Device Information* table..... 1
 - Updated R θ JA value: D = 124.5 to 124.6, all values in °C/W 5
 - Added *Application and Implementation* section..... 9
-

Changes from Revision L (May 2013) to Revision M (June 2023) Page

- Added *Package Information* table, *Pin Functions* table, *ESD Ratings* table, *Thermal Information* table, *Device Functional Modes*, *Device and Documentation Support* section, and *Mechanical, Packaging, and Orderable Information* section 1
 - Added BQA package to *Package Information* table..... 1
 - Updated thermal values for R θ JA: D = 86 to 124.5, PW = 113 to 147.7, all values in °C/W..... 5
 - Added thermal value for R θ JA: BQA = 88.3, all values in °C/W..... 5
-

Changes from Revision M (October 2023) to Revision N (February 2024) Page

- Updated R θ JA value: RGY = 47 to 87.1, all values in °C/W 6
-

Changes from Revision N (October 2023) to Revision O (February 2024) Page

- Updated thermal values for RGY package from R θ JA = 55.1 to 87.1, R θ JC(top) = 52.3 to 92.6, R θ JB = 49.4 to 30.9, Ψ JT = 14.6 to 2.4, Ψ JB = 31 to 61.7, R θ JC(bot) = 12.7 to 45.1, all values in °C/W 6
-

Changes from Revision M (June 2023) to Revision N (October 2023) Page

- Updated D and PW packages for R θ JC(top), R θ JB, Ψ JT, Ψ JB, and R θ JC(bot), all values in °C/W 6
-

Changes from Revision M (August 2023) to Revision N (February 2024) Page

- Added thermal values for D package: R θ JA = 124.6, R θ JC(top) = 79.7, R θ JB = 81.2, Ψ JT = 39.3, Ψ JB = 80.8, R θ JC(bot) = N/A, all values in °C/W 5
-

Changes from Revision M (May 2023) to Revision N (February 2024) Page

- Updated R θ JA values: RGY = 47 to 87.1, all values in °C/W 4
-

Changes from Revision L (July 2003) to Revision M (May 2023) Page

- Updated the *Features* section..... 1
 - Added the *Applications* section..... 1
 - Updated the numbering format for tables, figures, and cross-references throughout the document..... 1
 - Updated the *Device Information* table to include *Channel Count* 1
 - Added the *BQA* package to the data sheet..... 1
 - Added the *Pin Configuration and Functions* section..... 3
-

Changes from Revision Q (July 2023) to Revision R (October 2023) Page

- Updated title and format of *Device Information* table..... 1
 - Updated R θ JA values: D = 86 to 124.5, all values in °C/W 5
-

Changes from Revision Q (October 2023) to Revision R (February 2024) Page

- Updated R θ JA value: RGY = 47 to 87.1, all values in °C/W 5
-

Changes from Revision R (October 2023) to Revision S (February 2024) Page

- Updated thermal values for NS package from R θ JA = 90.7 to 120.9, R θ JC(top) = 48.3 to 78.2, R θ JB = 49.4 to 81.6, Ψ JT = 14.6 to 42.8, Ψ JB = 49.1 to 81.1, R θ JC(bot) = N/A, all values in °C/W 6
-

Changes from Revision Q (May 2023) to Revision R (October 2023) Page

- Updated R θ JA values: D = 90.6 to 124.5, PW = 122.6 to 147.7; Updated D and PW packages for R θ JC(top), R θ JB, Ψ JT, Ψ JB, and R θ JC(bot), all values in °C/W 6
-

Changes from Revision J (October 2023) to Revision K (February 2024) Page

- Deleted machine model from *Features* section..... 1
- Updated thermal values for D package from R θ JA = 90.6 to 124.6, R θ JC(top) = 50.9 to 79.7, R θ JB = 44.8 to 81.2, Ψ JT = 14.7 to 39.3, Ψ JB = 44.5 to 80.8, R θ JC(bot) = N/A, all values in °C/W 5

Changes from Revision I (August 2023) to Revision J (October 2023) Page

- Updated thermal values for PW package from R θ JA = 122.6 to 147.7, R θ JC(top) = 51.4 to 77.4, R θ JB = 64.4 to 90.9, Ψ JT = 6.7 to 27.2, Ψ JB = 63.8 to 90.2, all values in °C/W5

Changes from Revision C (May 2023) to Revision D (February 2024) Page

- Updated R θ JA value: D = 86 to 124.6, all values in °C/W 4

Changes from Revision B (June 2023) to Revision C (October 2023) Page

- Updated R θ JA values: PW = 113 to 147.7, all values in °C/W 5

Changes from Revision C (July 2023) to Revision D (February 2024) Page

- Updated R θ JA value: D = 86 to 124.6, all values in °C/W 4

Changes from Revision C (May 2023) to Revision D (February 2024) Page

- Updated R θ JA value: D = 86 to 124.6, all values in °C/W 4

Changes from Revision D (October 2023) to Revision E (February 2024) Page

- Updated R θ JA value: D = 86 to 124.6, all values in °C/W..... 4

Changes from Revision C (June 2023) to Revision D (October 2023) Page

- Updated R θ JA values: PW = 113 to 147.7, all values in °C/W.....4

Changes from Revision C (October 2023) to Revision D (February 2024) Page

- Updated RθJA values: D = 86 to 124.6, all values in °C/W 5

Changes from Revision B (June 2023) to Revision C (October 2023) Page

- Updated RθJA values: PW = 113 to 147.7, all values in °C/W 5

Changes from Revision C (October 2023) to Revision D (February 2024) Page

- Updated RθJA value: D = 86 to 124.6, all values in °C/W 5

Changes from Revision B (August 2023) to Revision C (October 2023) Page

- Updated RθJA values: PW = 113 to 147.7, all values in °C/W 5

Changes from Revision C (May 2023) to Revision D (February 2024) Page

- Added package size to *Package Information* table..... 1
- Updated RθJA value: D = 86 to 124.6, all values in °C/W 5

Changes from Revision C (June 2023) to Revision D (October 2023) Page

- Updated RθJA values: PW = 113 to 147.7, all values in °C/W..... 4
- Added Application and Implementation section..... 8

Changes from Revision O (October 2023) to Revision P (February 2024) Page

- Updated RθJA values: DB = 112.4 to 137.8, RGY = 63.8 to 87.1; Updated DB and RGY packages for RθJC(top), RθJB, ΨJT, ΨJB, and RθJC(bot), all values in °C/W..... 5

Changes from Revision K (June 2023) to Revision L (February 2024) Page

- Updated RθJA value: RGY = 47 to 87.1, all values in °C/W 6

The datasheet number will be changing.

Device Family	Change From:	Change To:
SNx4AHC00	SCLS227K	SCLS227M
SNx4AHCT04	SCLS232Q	SCLS232R
SNx4AHCT08	SCLS237O	SCLS237P
SNx4AHC32	SCLS247J	SCLS247L
SNx4AHC02	SCLS254L	SCLS254N
SNx4AHC74	SCLS255M	SCLS255N
SNx4AHC125	SCLS256M	SCLS256O
SNx4AHC126	SCLS257M	SCLS257N
SNx4AHCT02	SCLS262L	SCLS262N
SNx4AHCT74	SCLS263Q	SCLS263R
SNx4AHCT125	SCLS264Q	SCLS264R
SNx4AHCT126	SCLS265Q	SCLS265S
SN74AHC132	SCLS365I	SCLS365K
SN74AHCT126-Q1	SCLS506C	SCLS506D
SN74AHCT125-Q1	SCLS508B	SCLS508C
SN74AHCT32-Q1	SCLS528C	SCLS528D
SN74AHCT00Q-Q1	SGDS007C	SGDS007D
SN74AHC14Q-Q1	SGDS016C	SGDS016E
SN74AHC32Q-Q1	SGDS019B	SGDS019D
SN74AHC74Q-Q1	SGDS020B	SGDS020D
SN74AHCT08Q-Q1	SGDS021C	SGDS021D
SN74AHCT14Q-Q1	SGDS023C	SGDS023D
SNx4AHC14	SCLS238O	SCLS238P
SNx4AHC08	SCLS236K	SCLS236L

These changes may be reviewed at the datasheet links provided.

- <http://www.ti.com/product/SN74AHC00>
- <http://www.ti.com/product/SN74AHCT04>
- <http://www.ti.com/product/SN74AHCT08>
- <http://www.ti.com/product/SN74AHC32>
- <http://www.ti.com/product/SN74AHC02>
- <http://www.ti.com/product/SN74AHC74>
- <http://www.ti.com/product/SN74AHC125>
- <http://www.ti.com/product/SN74AHC126>
- <http://www.ti.com/product/SN74AHCT02>
- <http://www.ti.com/product/SN74AHCT74>
- <http://www.ti.com/product/SN74AHCT125>
- <http://www.ti.com/product/SN74AHCT126>
- <http://www.ti.com/product/SN74AHC132>
- <http://www.ti.com/product/SN74AHCT126>
- <http://www.ti.com/product/SN74AHCT125-Q1>
- <http://www.ti.com/product/SN74AHCT32-Q1>
- <https://www.ti.com/product/SN74AHCT00Q-Q1>
- <https://www.ti.com/product/SN74AHC14Q-Q1>
- <https://www.ti.com/product/SN74AHC32Q-Q1>
- <https://www.ti.com/product/SN74AHC74Q-Q1>
- <https://www.ti.com/product/SN74AHCT08Q-Q1>
- <https://www.ti.com/product/SN74AHCT14Q-Q1>
- <https://www.ti.com/product/SN54AHC14>
- <https://www.ti.com/product/SN54AHC08>

Reason for Change:			
Datasheet update driven by changes announced in PCN 20231219000 and 20230927000			
Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):			
No anticipated impact. This is a specification change announcement only.			
Changes to product identification resulting from this PCN:			
None.			
Product Affected:			
Devices included in PCN 20231219000			
SN74AHC02DR	SN74AHC00RGYR	SN74AHC14QDRQ1	SN74AHC74RGYRG4
SN74AHC32DR	SN74AHC08RGYR	SN74AHC32QDRQ1	SN74AHCT00QDRQ1
SN74AHC126DR	SN74AHC14RGYR	SN74AHC74QDRQ1	SN74AHCT08QDRQ1
SN74AHC132DR	SN74AHC74RGYR	SN74AHCT02RGYR	SN74AHCT125RGYR
SN74AHC14DBR	SN74AHCT04NSR	SN74AHCT126NSR	SN74AHCT32QDRQ1
SN74AHCT126QDRQ1	SN74AHC125RGYR	SN74AHCT08QDRG4Q1	
Datasheet Only			
SN74AHCT74D	SN74AHCT08DRG4	SN74AHC32QDRG4Q1	SN74AHCT14QPWRQ1
SN74AHC32PWR	SN74AHCT126PWR	SN74AHC74QDRG4Q1	SN74AHC14QPWRG4Q1
SN74AHCT08DR	SN74AHC14QPWRQ1	SN74AHCT125QPWRQ1	SN74AHC32QPWRG4Q1
SN74AHCT74DR	SN74AHC32QPWRQ1	SN74AHCT32QDRG4Q1	SN74AHC74QPWRG4Q1
SN74AHC132PWR	SN74AHC74QPWRQ1	SN74AHCT126QDRG4Q1	SN74AHCT00QDRG4Q1
SN74AHC132DRE4	SN74AHCT14QPWRG4Q1		

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.

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